

LAPIS Semiconductor Errata

ML620Q500H Series

Issue date: Oct. 16th 2015



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1. Introduction

A part of functions on ML620Q500H Series (ML620Q503H/504H) has a bug. And User's manual has defective descriptions. This document describes the details and the workaround.

Target User's manual: FEUL620Q504H-01

1.1 Issue List

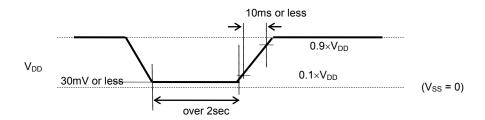
No.	Issue Date	Update	Subject	
1	2015.10.16	-	Power-down/on Procedures	
2	2015.10.16	-	Memory mapping of ML620Q503H	

2. Detail Description

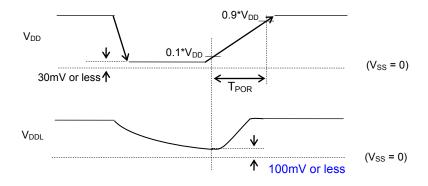
2.1 Power-down/on Procedures

A Power-on procedures and constraints are modified (in Appendix C. of the User's manual).

(Previous procedures and consraints)



(Modified procedures and consraints)



Note:

If V_{DDL} level is 100 mV or more over, reset the IC by RESET_N pin after power-on.

2.2 Memory mapping of ML620Q503H

Memory mapping of ML620Q503H is modified (in section 2. CPU and Memory Space of the User's manual).

(Previous mapping):

CSR:PC	Code segment 0		
0:0000H	Vector table		
	or		
0:00FFH	Program code		
0:0100H			
	Program code		
0:7BFFH			
0:7COOH	Test data area		
0:7DFFH	(Rewritable)		
0:7E00H	Test data area		
0:7FFFH	(Not rewritable)		
	8bit		

(Modified mapping):

CSR:PC	Code segment 0		
0:0000H	Vector table		
	or		
0:00FFH	Program code		
0:0100H			
	Program code		
0:7BFFH			
0:7C00H			
	Unused area		
0:0FBFFH			
0:0FC00H	T		
• • • • • • • • • • • • • • • • • • • •	Test data area		
0:OFDFFH	(Rewritable)		
0:0FE00H	Test data area		
0:0FFFFH	(Not rewritable)		
	8bit		

Revision History

	Issue date	Page		
Document No.		Before	After	Description
		revised	revised	
15LD-1070-01E	2015.10.16	_	_	First revision